

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC2336HMS-18PBF

(Engineering Calculation)

MSOP

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TOTAL MASS (g): 0.037335

| COMPONENT MATERIAL | VENDOR/INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL Pkg. | | |
|---------------------------|----------------------------------|-------------------|--------------------------------|----------------------|-------------------------------|---------------------------------|----------------------|---------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003058 | 1000000 | 81907.0078125 | | |
| Die Coat | Dow Corning | Silicone | 69830-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 37083.4375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000355 | 25000 | 9508.49804688 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 107.138008118 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 26784503.1738 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | | Lead Frame Total: | | 0.014214 | 1001000 | 380714.90625 | |
| Plating | PMI | Enter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Enter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 1901.76640625 | | |
| | | | External Plating Total: | | 0.000710 | 1000000 | 1901.76640625 | |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 2303.46704102 | | |
| | | | Internal Plating Total: | | 0.000086 | 1000000 | 2303.46704102 | |
| Die Attach | ELECTRICALLY INSULATING ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000010 | 50000 | 26784503.1738 | | |
| | | Iridium (Ir) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000061 | 300000 | 1633.85401426 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000133 | 650000 | 3562.33862508 | | |
| | | | Die Attach Total: | | 0.000204 | 1000000 | 5464.02857422 | |
| | | Encapsulation | MULTIAROMATIC RESIN B/SB-FREE | Resin (EP) | | 0.002439 | 130000 | 65327.3964375 |
| | | | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 |
| Silica (SiO2) | 60676-86-0 | | | 0.015571 | 830000 | 417061.46875 | | |
| Antimony Trioxide (Sb2O3) | 1309-64-4 | | | 0.000000 | 0 | 0 | | |
| Metal Hydroxide | | | | 0.000657 | 35000 | 17597.4179688 | | |
| Carbon Black (C) | 1333-86-4 | | | 0.000094 | 5000 | 2517.74316406 | | |
| | Encapsulation Total: | | 0.018761 | 1000000 | 502504.0625 | | | |
| Bond Wire Estimated | APW/TANAKA/Kn | Gold (Au) | 7440-57-5 | 0.000302 | 1000000 | 8088.91943359 | | |

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